

2.4 to 2.5 GHz RF FEM

RFIC 2019.05 Update Rev1.2

DESCRIPTION

The AP1286S is a linear, low current consumption RF Front-End Module (FEM) which consists of power amplifier, low noise amplifier and two T/R switches for ISM band wireless application. It offers highly integrated Input / Output matching on chip to reduce the bill of material. This RF FEM is developed for portable product of ISM band, and compact device or embedded module application of IoT with stable and outstanding performance.

AP1286S is housed in a 3 x 3 (mm), 16-pin, QFN leadless package, a high performance FEM.

KEY FEATURES

Tx:

· Low current :

37mA for 10dBm 3.3V FSK application 75mA for 18dBm 3.3V FSK application 91mA for 20dBm 3.3V FSK application

Rx:

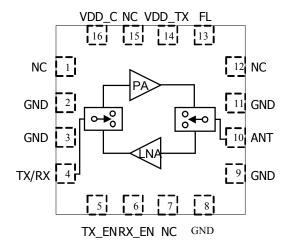
- Low current : 13mA for 3.3V application
- Low Noise Figure : 2dB

Pin Details

Major Applications

- 802.15 PANs extended range device
- 2.4 GHz ISM Band portable device
- 2.4 GHz IoT Gateway device
- RF4CE application

Pin Assignment



QFN-16pin, 3x3 (mm)

Pin Number	Name	Description
1	NC	No-used pin
2	GND	Connected to ground
3	GND	Connected to ground
4	TX/RX	RF signal from/to transceiver
5	TX_EN	Control signal input for TX path enable
6	RX_EN	Control signal input for RX path enable
7	NC	No-used pin
8	GND	Connected to ground
9	GND	Connected to ground
10	ANT	Antenna connection pin
11	GND	Connected to ground
12	GND	Connected to ground
13	FL	Keep Floating
14	VDD_TX	Supply voltage connection pin for TX
15	NC	No-used pin
16	VDD_C	Supply voltage connection pin for TX/RX
17	Center GND	IC center pad connected to ground

For more information, please contact us at:

Sales Dept.

Tel: +886-2-2698-1022

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Tx Electrical Characteristics for general ISM band application

VDD_C = VDD_TXTX_EN = 3.3V; RX_EN = 0V; CW signal; TA = 25°C; unless otherwise noted.

	Specification					
Parameter	Min	Тур.	Max	Units	Notes	
Freq	2.4		2.5	GHz		
Input return loss		10		dB		
Output return loss		5.5		dB		
P1dB		20.5		dBm		
Saturation Power			22	dBm		
Small Signal Gain		23	26	dB		
PAE		35		%	@ Pout = P1dB	
2 nd Harmonics		-23		dBm/MHz	@ Pout = 20dBm	
3 rd Harmonics		-22		dBm/MHz	@ Pout = 20dBm	
Iref		0.25		mA	@ Pout = P1dB	
Current Consumption		91		mA	@ Pout = 20dBm	
		75			@ Pout = 18dBm	
		56			@ Pout = 15dBm	
		37			@ Pout = 10dBm	

Rx Electrical Characteristics for general ISM band application

VDD_C = RX_EN = 3.3V; TX_EN = 0V; CW signal; TA = 25°C; unless otherwise noted.

	Specification				
Parameter	Min	Тур.	Max	Units	Notes
Freq	2.4		2.5	GHz	
Small Signal Gain		13		dB	
Noise Figure		2		dB	
Current Consumption		12		mA	
Input Return Loss		5		dB	
Output Return Loss		9		dB	
OP1dB		7		dBm	

RFIC Technology Corp. reserved the right to make any changes to the specifications without notice.



Caution: ESD Sensitive

Appropriate precaution in handling, packaging And testing devices must be observed.

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Absolute Maximum Ratings

<u>Parameter</u>	Rating	<u>Unit</u>
DC Power Supply For Drain	+4	V
DC Supply Current For Drain	300	mA
RF Input Power	+5	dBm
Operating Ambient Temperature	-40~85	°C
Storage Temperature	-40~125	°C
ESD (HBM, JESD22-A114, all pins)	300	V
Moisture Sensitivity	MSL3	

Logic Control Table

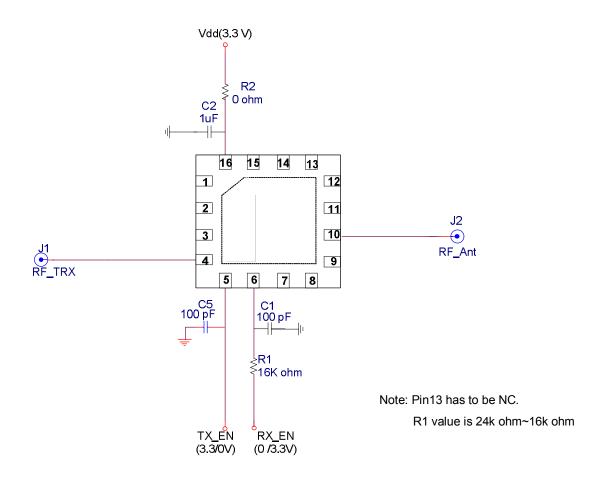
TX_EN	RX_EN	<u>State</u>	
1	0	TX Active	
0	1	RX Active	

Note:

1'' = +3V to +3.3V

"0" = +0V to +0.2V

ISM Band General Application Reference Circuit



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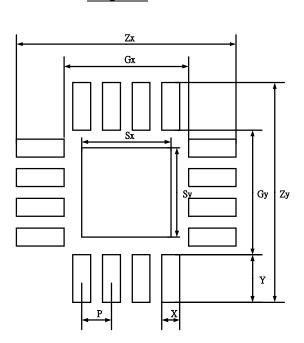
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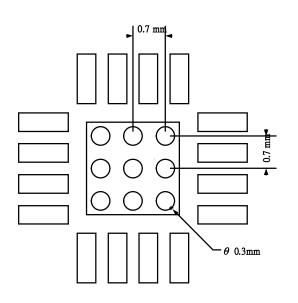
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Suggested PCB Layout

I/O Pin, Central PAD Layout



Thermal PAD Via Design



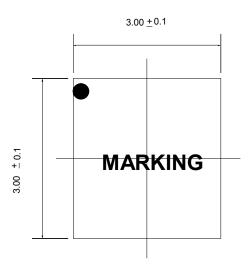
PCB Footprint Dimension (mm)								
P X Y Sx Sy Gx Gy Zx Zy							Zy	
0.5	0.3	0.85	1.5	1.5	2.1	2.1	3.8	3.8

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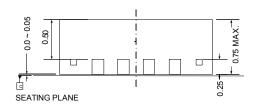
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Package Outline

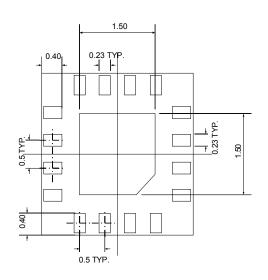
Top View



Side View



Bottom View



Unit: mm

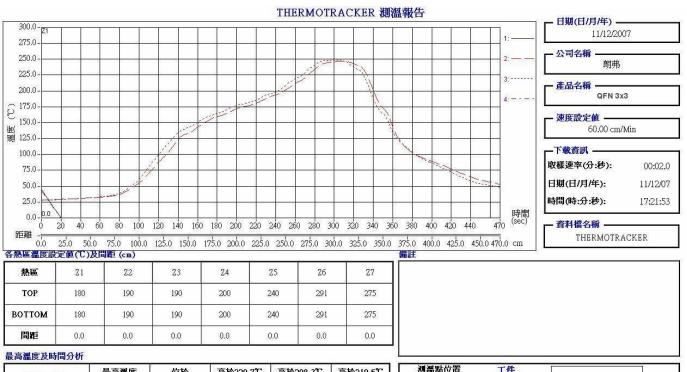
Note:

- 1. Dimension and tolerance conform to ASME Y14.5M-1994.
- 2. Refer to JEDEC STD. MO-220 WEED-2 ISSUE B

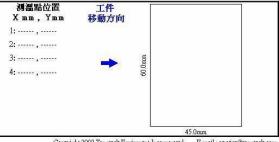
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Recommended Solder Reflow Profile



测温點名稱	最高溫度 (℃)	位於 (秒)	高於220.7℃ 的時間(秒)	高於208.3℃ 的時間(秒)	高於210.6℃ 的時間(秒)
1	44.2	0.00	0.00	0.00	0.00
	247.2	308.00	64.00	82.00	78.00
	248.8	302.00	68.00	86.00	84.00
	42.1	0.00	0.00	0.00	0.00
	4		0		6
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AP1286S



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The product is designed and manufactured for consumer application only and is not intended for any application listed below which requires especially high reliability for the prevention of such defect which could lead to personal injury, death, physical or environmental damage.

- Aircraft equipment.
- Aerospace equipment.
- Undersea equipment.
- Medical equipment.
- Life-saving or life-sustaining applications
- Transportation equipment (vehicles, trains, ships, etc.).
- Traffic signal equipment.
- Disaster prevention / crime prevention equipment.
- Application of similar complexity and/ or reliability requirements to the applications listed in the above.

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